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SunLED XEMG2500D

For any questions, you can email us directly: <u>sales@integrated-circuit.com</u>



Part Number: XEMG2500D

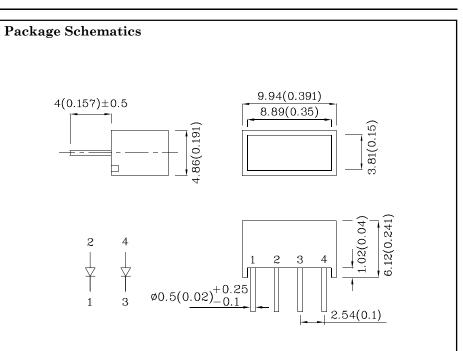
8.89mmx3.81mm LED LIGHT BAR

Features

- Robust package
- Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- RoHS compliant



RECOMMENDED PCB LAYOUT



Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01")$ unless otherwise noted. 2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	MG (GaP)	Unit		
Reverse Voltage	V_{R}	5	V	
Forward Current	$\mathbf{I}_{\mathbf{F}}$	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA	
Power Dissipation	P_{D}	62.5	mW	
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$		
Storage Temperature	Tstg	$-40 \sim +85$	°C	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

Operating Characteristics (T _A =25°C)	MG (GaP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	$V_{\rm F}$	2.2	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V
Reverse Current (Max.) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λP	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	$_{ m pF}$

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I _F =20mA) mcd		Wavelength CIE127-2007* nm λΡ	Lens-color
			min.	typ.		
XEMG2500D	Green	GaP	12 5*	25 9*	565*	Green Diffused

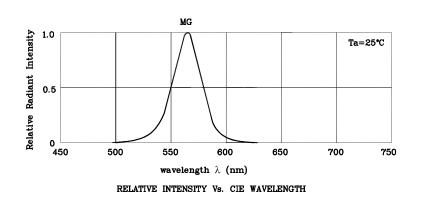
*Luminous intensity value and wavelength are in accordance with CIE127-2007 Mar 05,2014

XDSA1974 V6-X Layout: Maggie L.

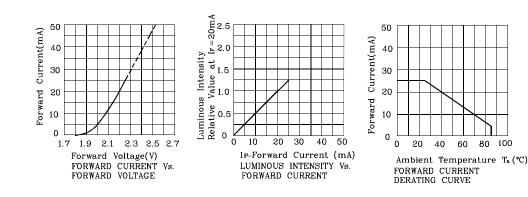


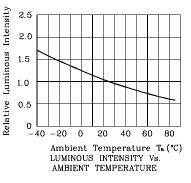
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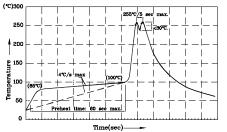


♦ MG





Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



eat temperature of 105°C or less (as hed to the LED pins) prior to immer num solder bath temperature of 260° mend pre-heat occuple attache with a maximum wave soldering C for 3 sec (5

max). 3.Do not apply stress to the epoxy resin while the temperature is a 4.Fixtures should not incur stress on the component when mounting during soldering process. 5.SAC 305 solder alloy is recommended. 6.No more than one wave soldering pass. 7.During wave soldering, the PCB top-surface temperature should be kept below 105°C.

Remarks:

If special sorting is required (e.g. binning based on forward voltage,

luminous intensity / luminous flux, or wavelength),

- the typical accuracy of the sorting process is as follows:
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

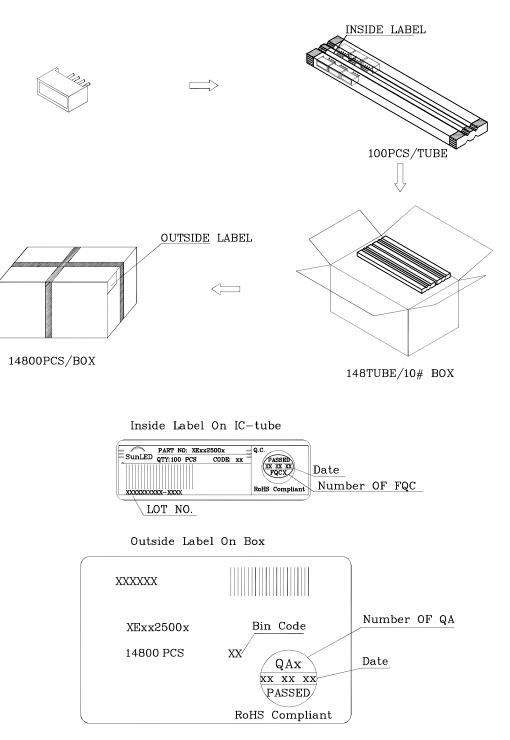
Note: Accuracy may depend on the sorting parameters.



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PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp

Mar 05,2014